

Discription

The HCESD1006LC5VBL-M protects sensitive semiconductor	
components from damage or upset due to electrostatic	2
discharge (ESD) and other voltage induced transient events.	
Excellent clamping capability, low leakage, low capacitance,	HXY
and fast response time provide best in class	
protection on designs that are exposed to ESD.	
It gives designer the flexibility to protect one bi-directional	
line in applications where arrays are not practical.	DFN1006-2L

Features

- ★ Ultra Low Capacitance 2.5 pF
- ★ Low Clamping Voltage
- ★ Small Body Outline Dimensions: 0.039" x 0.024" (1.00 mm x 0.60 mm)
- ★ Low Body Height: 0.020" (0.5 mm)
- ★ Stand-off Voltage: 5 V
- ★ Low Leakage
- ★ Response Time is Typically < 1.0 ns
- ★ IEC61000-4-2 Level 4 ESD Protection
- ★ This is a Pb-Free Device

Orderingin formation



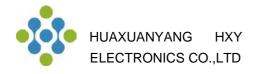


Circuit Diagram

Product ID	Pack	Qty(PCS)
HCESD1006LC5VBL-M	DFN1006-2L	10000

Absolute Ratings(Tamb = 25°C)

Symbol	Parameter	Value	Units
P _{PP}	Peak Pulse Power (t _p = 8/20 µ s)	30	W
TL	Maximum lead temperature for soldering during 10s	260	°C
T _{stg}	Storage Temperature Range	-55 to +150	°C
T _{op}	Operating Temperature Range	-55 to +150	°C
Tj	Maximum junction temperature	150	°C
	IEC61000-4-2 (ESD) air discharge contact discharge	土10 土15	κv



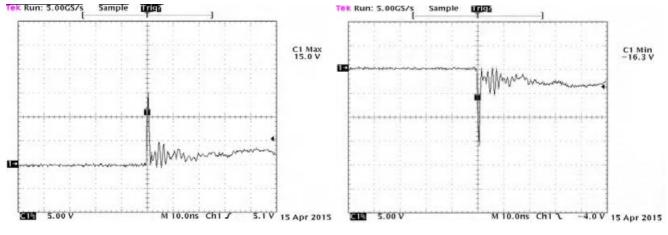
Device	V _{RWM} (V)	I _R (μA) @V _{RWM}		(V) * = 1mA	I _{PP} (A)**	V _C (V) ** @ I _{PP} = 1A	Р _{РК} (W)**	C(pF) VR=0V, f=1MHz;
	Max	Max	Min	Max	Max	Max	Max	Тур
HCESD1006LC5VBL-M	5.0	1.0	5.5	8.5	2.5	10	30	2.5

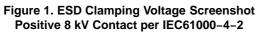
Electrical Characteristics (T_A = 25°C unless otherwise noted)

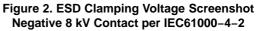
* V_{BR} is measured with a pulse test current I_T at an ambient temperature of 25°C.

** Surge current waveform per Figure 1.

Typical Characteristics

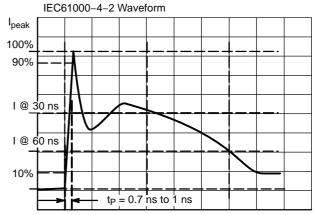




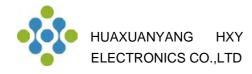


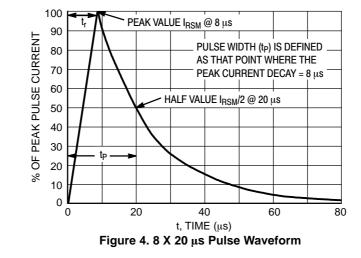
IEC 61000-4-2 Spec.	IEC	6100	00-4-2	2 Spec.
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Level	Test Voltage (kV)	First Peak Current (A)	Current at 30 ns (A)	Current at 60 ns (A)
1	2	7.5	4	2
2	4	15	8	4
3	6	22.5	12	6
4	8	30	16	8



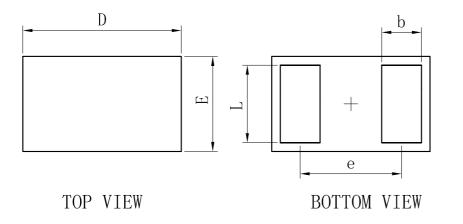




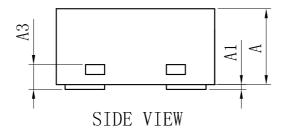




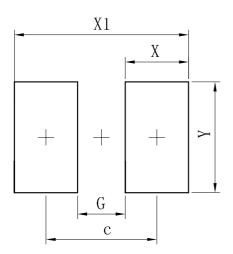
Outline And Dimensions



DFN1006-2L						
Dim	Min	Min Typ Max				
D	0.95	1.00	1.05			
Е	0.55	0.60	0.65			
е	_	0.64	-			
L	0.44 0.49 0.54					
b	0.20 0.25 0.3					
А	0.43 0.48 0.5					
A1	0 – 0.05					
A3	0. 127REF.					
All Dimensions in mm						



Soledering Footprint



Dimensions	(mm)
С	0.70
G	0.30
Х	0.40
X1	1.10
Y	0.70



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